IEC Electronics Analysis & Testing Laboratory has solutions for your most complex design or supply chain challenges. From one-time testing to fully integrated turn-key supply chain management, we provide services to solve challenges, minimize risk, and deliver solutions customized to your needs.

**Solve Challenges**

*Electronics Manufacturing Experience*
Unique analysis due to end use application knowledge

*Multi-disciplinary Approach*
On-site engineering and supply chain expertise

*Forensic-style Investigation*
Methodical and detailed approach to finding the right solution

**Minimize Risk**

*High-quality Testing Standards*
Only EMS with on-site lab approved by the DLA for their QTSL program

*Tailored Testing Plan*
State-of-the-art equipment to develop a custom approach to your specific needs

*Expert Team*
Staff members with over 25 years of counterfeit component risk mitigation and methodology experience

**Deliver Solutions**

*Quick Turnaround Time*
Dedicated staff to respond to your urgent needs

*Flexible Solutions*
Services available for electronic components, integrated circuits, or printed circuit boards

*Seamless Integration with Manufacturing*
Lab on-site with 72,000 square foot EMS facility

**Root-Cause Failure Analysis**
Identify the source of quality and reliability issues.
Solutions for:
- Product Design Failure, Low Yields, Poor Performance, Degradation

**Inspection & Authenticity Testing**
Validate quality and integrity of components against approved devices and minimize risk to your supply chain.
Capabilities:
- Counterfeit Component Detection,
- Lot Acceptance, Construction Analysis,
- Obsolescence Management

**Reliability & Qualification Services**
Ensure the fitness of a device for use in the field.
Capabilities:
- Up-screening, Destructive Physical Analysis (DPA), Environmental & Accelerated Life Testing, Burn-In, Construction Analysis

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ISO/IEC 17025:2017 Accredited
Non Destructive Testing

**TESTING PROCEDURE**
- Up-screening
- Optical Inspection
- X-Ray Inspection
- Scanning Acoustic Microscopy
- X-Ray Fluorescence
- Seal Testing
- Scanning Electron Microscope/EDS
- Particle Impact Noise Detection
- FTIR Spectroscopy
- Solderability Testing
- Thermal Cycling
- Electrical Testing
- HAST
- Reflow Profiling

**APPLICABLE METHODS**
- MIL-STD-202
- MIL-STD-883, 750, AS6081
- MIL-STD-883, 750, 202
- IPC/JEDEC J-STD-005
- AS6081, JEDS213, IPC-4552
- MIL-STD-883, 750, 202
- MIL-STD-883, 750
- MIL-STD-883, 750
- ASTM E 334, ASTM E 1131
- J-STD
- MIL-STD-883, 750
- AS6081, MIL-STD-883
- Customized per Application
- Customized per Application

Destructive Testing

**TESTING PROCEDURE**
- Cross-section Analysis
- Mechanical Decapsulation
- Chemical Decapsulation
- Wire Bond Pull
- Die Shear
- Dye Penetrant
- Resistance to Solvents
- Black Top Evaluation
- TGA Analysis
- Coupon Testing
- Die Cross-section
- Component removal from board

**APPLICABLE METHODS**
- Customized per Application
- Customized per Application
- MIL-STD-883, 750, AS6081/6171
- MIL-STD-883, 750, AS6081/6171
- Customized per Application
- Customized per Application
- IDEA 1010, AS6081/6171
- IDEA 1010, AS6081/6171
- ASTM E 334, ASTM E 1131
- Customized per Application
- Customized per Application
- Customized per Application

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